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FIG. 1

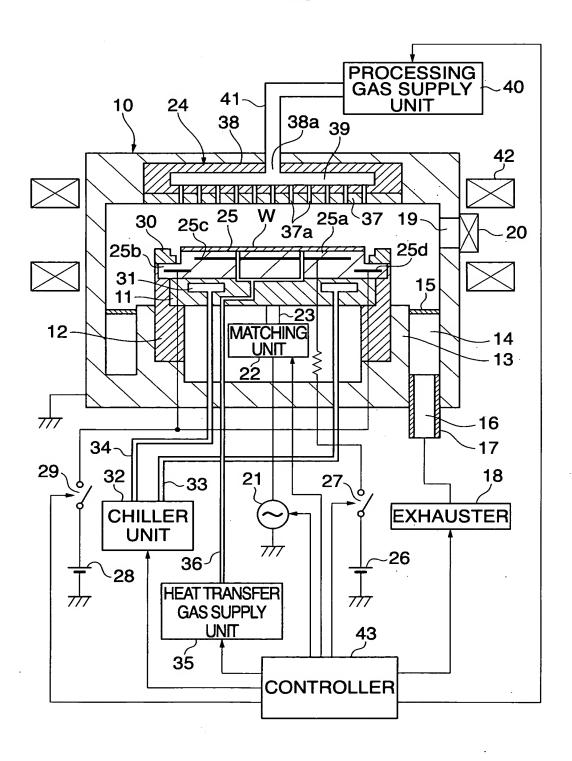


FIG. 2

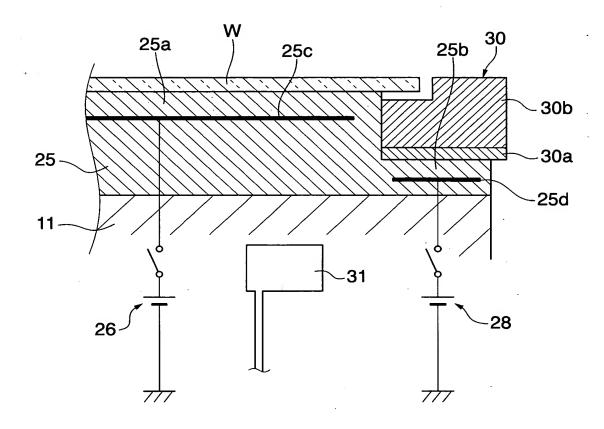


FIG. 3

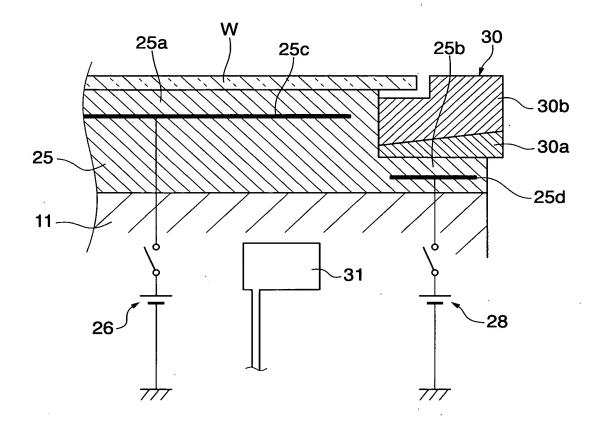


FIG. 4

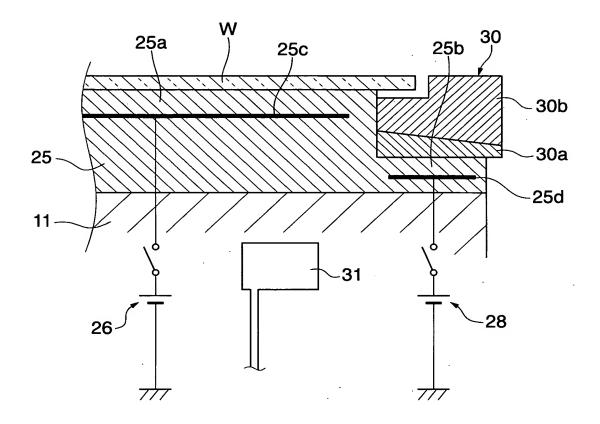
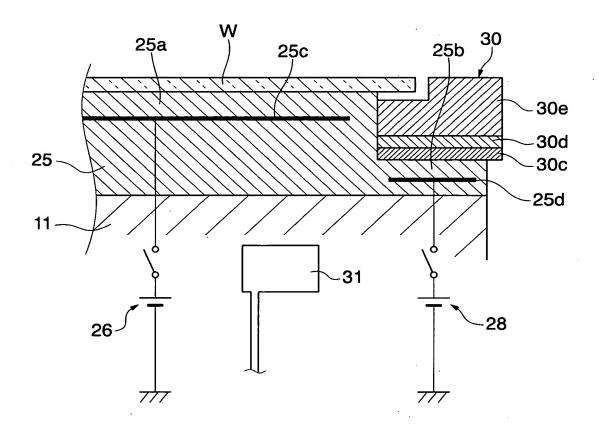
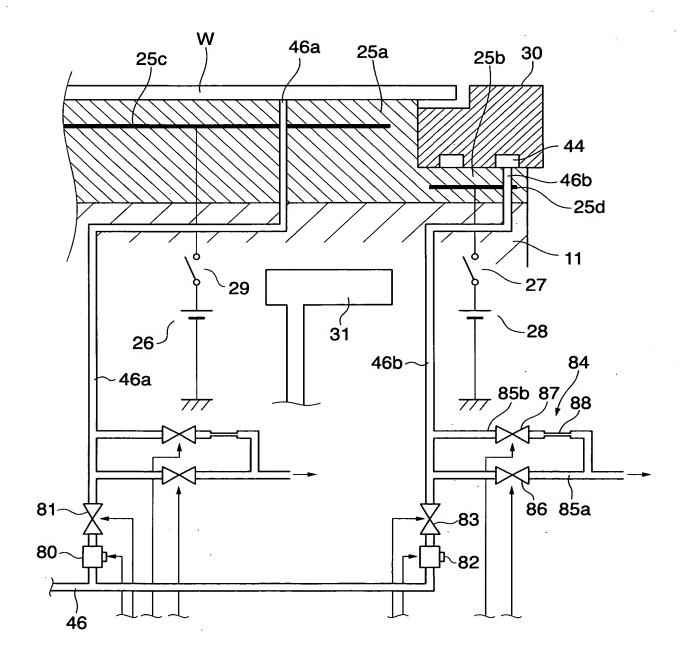


FIG. 5



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FIG. 6



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FIG. 7A

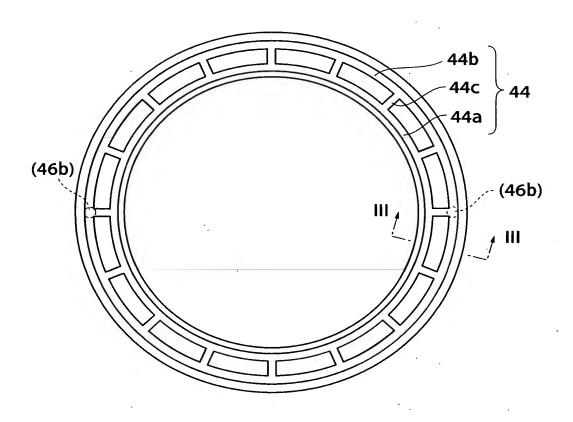
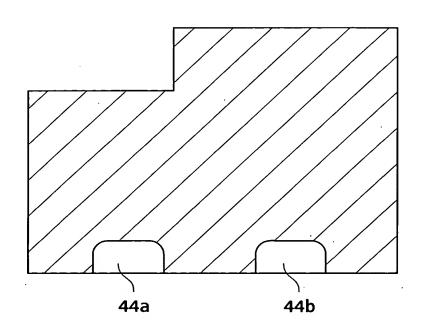
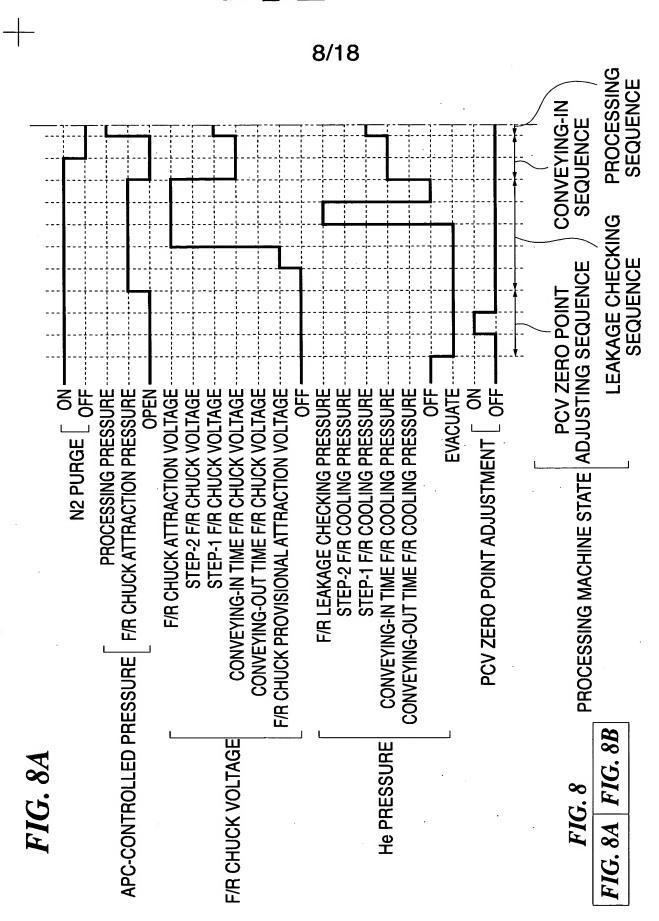


FIG. 7B





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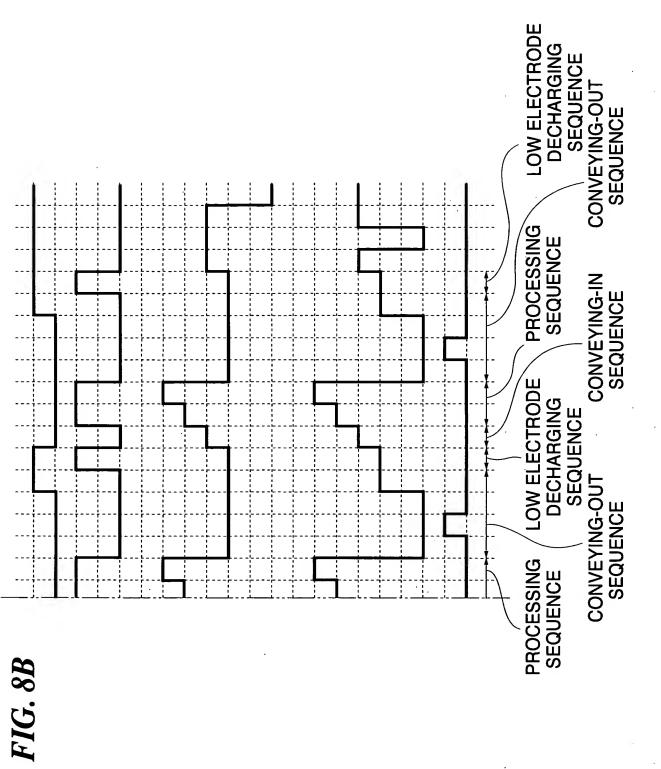


FIG. 9

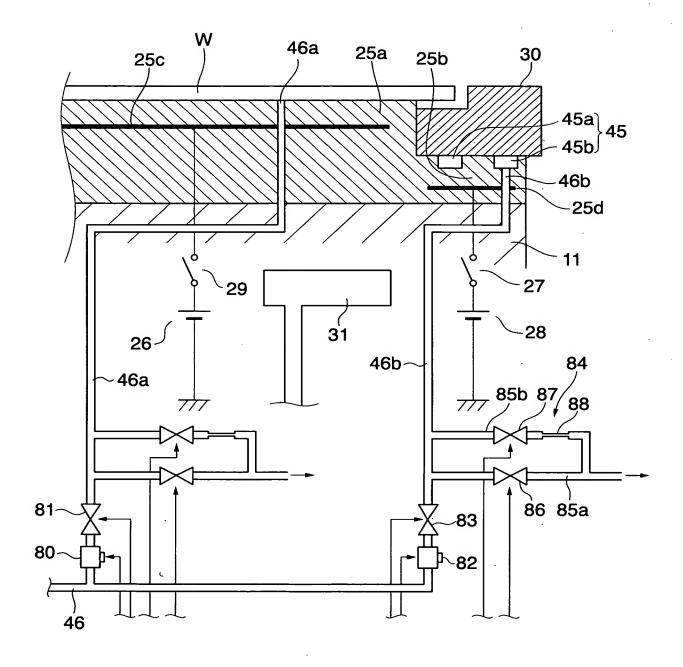
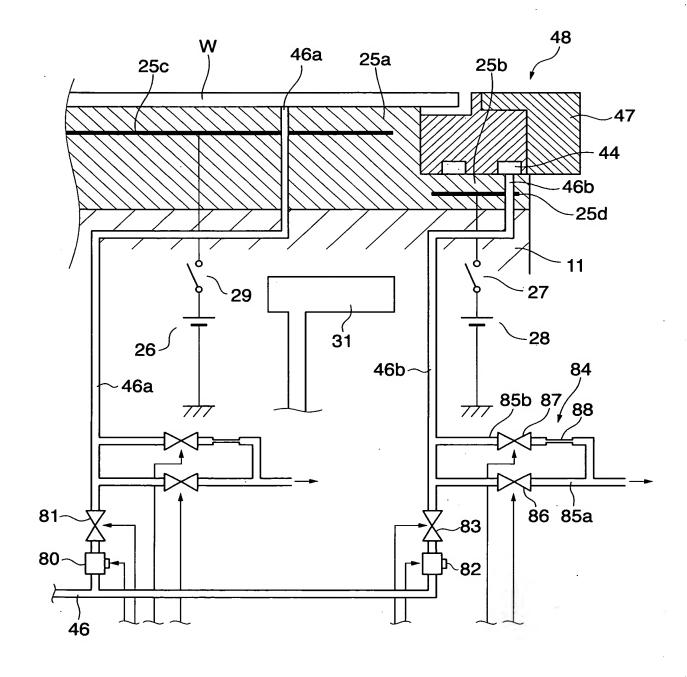


FIG. 10



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FIG. 11

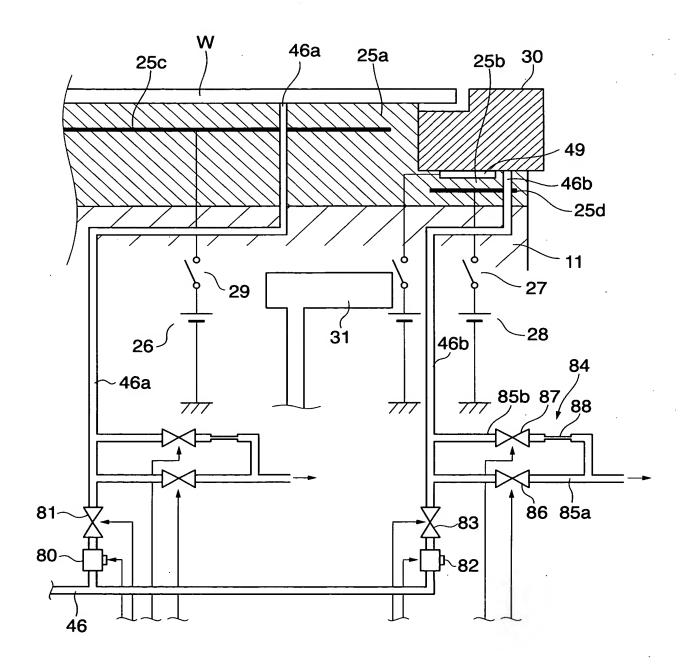
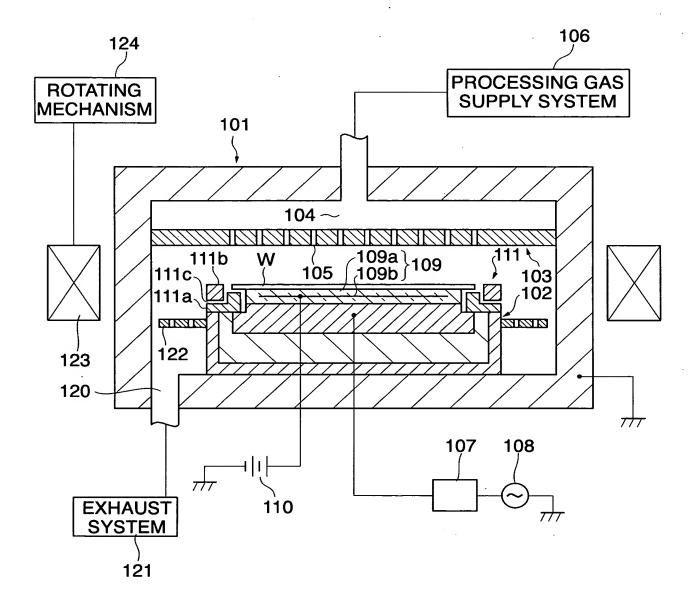


FIG. 12



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FIG. 13

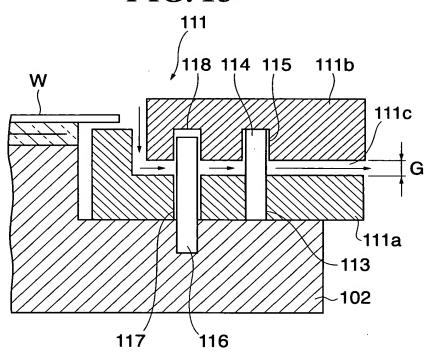
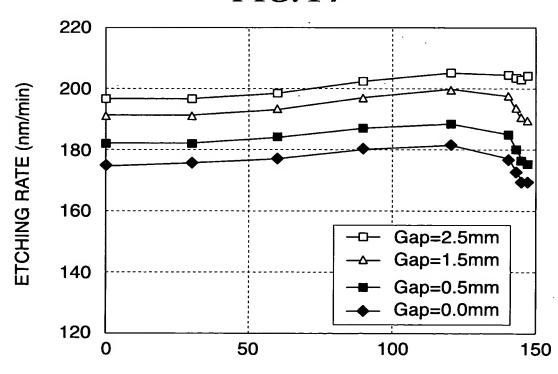
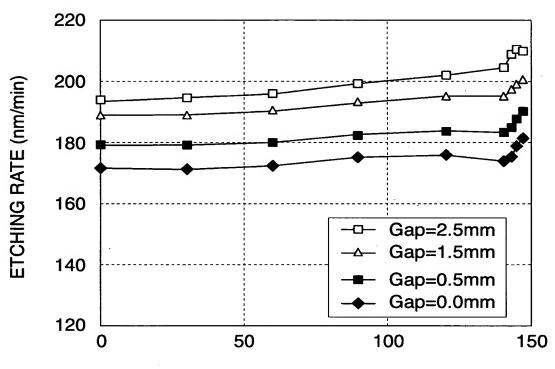


FIG. 14



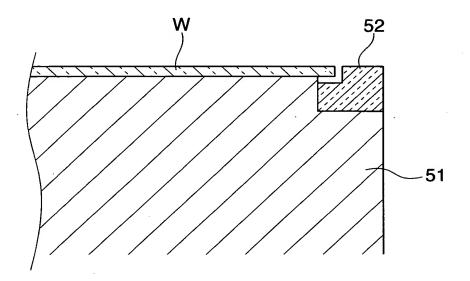
DISTANCE FROM CENTER OF WAFER (mm)

FIG. 15



DISTANCE FROM CENTER OF WAFER (mm)

FIG. 16

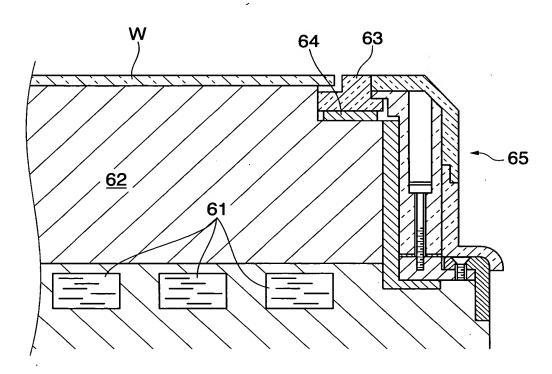


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FIG. 17

<u>66</u>



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